

December 8, 2017

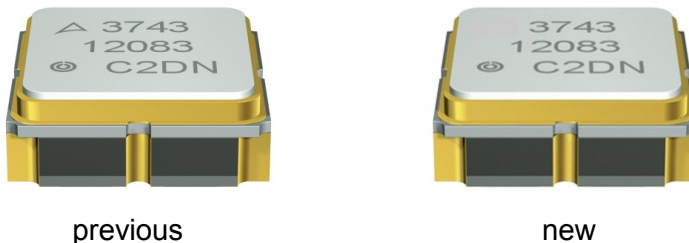
PCN

RF360 SAW components in ceramic SMD packages for automotive electronics

1) RF360 AE SMD components

The EPCOS logo will be removed from the upper left corner of the marking of RF360 SAW components in ceramic SMD packages for automotive electronics. All other marking elements (i.e. part number, lot number and date code) will remain unchanged.

Fig: Comparison of markings on ceramic SMD components



previous

new

Affected products

Ordering code	Ordering code	Ordering code
B39*R*	B39232B1644U510	B39800X3403H810
B39*B33*	B39232B1646U410	B39162B4050U510
B39*B34*	B39152B1647U510	B39162B4060U810
B39*B35*	B39152B1664U410	B39192B4143U410
B39*B37*	B39152B1669U410	B39841B4147U410
B39*B39*	B39*B17*	B39881B4146U510

For components with existing marking:

Deadline for last orders: December 31, 2018
 Last shipments by: April 30, 2019

December 8, 2017

2) RF360 AE SMD components with PSN passivation, LT-Zer0-TCF and HQTCF

As part of our efforts to further consolidate production processes and to serve the increasing demand for RF360 SAW components, 6-inch wafer material will replace the 4-inch wafer material used in the front-end production processes for SMD components with pyrolytic silicon nitride passivation (PSN), LT-Zer0-TCF (LT) and HQTCF (LN) for automotive electronics.

Affected products

Ordering code	Ordering code	Ordering code
B39162B3400U410	B39871B3441U410	B39162B3525U510
B39162B3401B710	B39232B3442U410	B39232B3526U510
B39232B3404U410	B39871B3443U410	B39162B3528U510
B39162B3405H910	B39761B3444Z810	B39232B3595U410
B39162B3413U410	B39761B3445U410	B39122B3596U410
B39152B3421U410	B39931B3446U410	B39242B3912U410
B39162B3423U410	B39232B3447U410	B39162B3913U410
B39162B3424U410	B39871B3448U510	B39931B3916U410
B39232B3425U510	B39162B3470H910	B39242B3918U410
B39511B3426U410	B39232B3471H910	B39232B3920U510
B39481B3427U410	B39921B3474H910	B39931B3921U410
B39132B3428U410	B39731B3479B510	B39162B3923U410
B39911B3429U410	B39162B3517U510	B39931B3926U410
B39871B3430U410	B39162B3519U410	B39232B3927U510
B39921B3432U410	B39162B3524B710	B39761B3929U410
B39871B3440U410		

For components with 4-inch wafer material:

Deadline for last orders: December 31, 2018
 Last shipments by: April 30, 2019

December 8, 2017

The announced changes will be effective for released as well as for newly designed components.

There will be no impact on product quality, specification or delivery performance. The components will be qualified according to AEC-Q200 based on reference types.

Enclosure PCN (ID No. M306)

Contact Michael Loeffler, RF360 D AE PM, Munich

Customers are asked to address inquiries directly to their sales contacts.

Product / Process Change Notification

1. ID No.: M306		2. Date of announcement: December 8, 2017
3. Product / product group: 1) SAW AE SMD components 2) SAW AE SMD components with PSN passivation, LT-Zer0-TCF and HQTCF		
Old ordering code: 1) SAW AE SMD components: B39*R* B39*B33* B39*B34* B39*B35* B39*B37* B39*B39* B39232B1644U510 B39232B1646U410 B39152B1647U510 B39152B1664U410 B39152B1669U410 B39*B17* B39800X3403H810 B39162B4050U510 B39162B4060U810 B39192B4143U410 B39841B4147U410 B39881B4146U510 2) SAW AE SMD components with PSN passivation, LT-Zer0 TCF and HQTCF: B39162B3400U410 B39162B3401B710 B39232B3404U410 B39162B3405H910 B39162B3413U410 B39152B3421U410 B39162B3423U410 B39162B3424U410 B39232B3425U510 B39511B3426U410 B39481B3427U410 B39132B3428U410 B39911B3429U410	New ordering code: no change	Customer part number:

B39871B3430U410 B39921B3432U410 B39871B3440U410 B39871B3441U410 B39232B3442U410 B39871B3443U410 B39761B3444Z810 B39761B3445U410 B39931B3446U410 B39232B3447U410 B39871B3448U510 B39162B3470H910 B39232B3471H910 B39921B3474H910 B39731B3479B510 B39162B3517U510 B39162B3519U410 B39162B3524B710 B39162B3525U510 B39232B3526U510 B39162B3528U510 B39232B3595U410 B39122B3596U410 B39242B3912U410 B39162B3913U410 B39931B3916U410 B39242B3918U410 B39232B3920U510 B39931B3921U410 B39162B3923U410 B39931B3926U410 B39232B3927U510 B39761B3929U410		
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4. Description of change:

1) RF360 SAW AE SMD components:

The EPCOS logo will be removed from the upper left corner of the marking of RF360 SAW components in ceramic SMD packages for automotive electronics. All other marking elements (i.e. part number, lot number and date code) will remain unchanged.

2) RF360 SAW AE SMD components with PSN passivation, LT-Zer0-TCF and HQTCF:

As part of our efforts to further consolidate production processes and to serve the increasing demand for RF360 SAW components, 6-inch wafer material will replace the 4-inch wafer material used in the front-end production processes for SMD components with pyrolytic silicon nitride passivation (PSN), LT-Zer0-TCF (LT) and HQTCF (LN) for automotive electronics.

5. Effect on the product or for the customer (benefit / quality, specification, lead time):

The changes have no effect on product quality, specifications, ordering codes or delivery performance. There is no change of packages or packing.

6. Quality assurance measures / risk assessment:

All types that change wafer size will be re-qualified according to AEC Q200 (by representative types) prior to sampling and volume production.

7. Scheduled date of change:

For both changes:

Deadline for last orders of components with current marking / wafer size (LTB):
December 31, 2018

Deadline for last shipments (LTS):
April 30, 2019

Please note that all customers holding PPAPs and other qualification documents (mainly automotive customers) will be addressed separately by RF360 Sales.

8. Estimated date of first delivery of changed product: January 1, 2019

If RF360 does not receive notification to the contrary within a period of 10 weeks, RF360 assumes that the customer agrees to the change. For an interim period we cannot rule out that old as well as new products will be shipped

Quality Management

Signature

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signed: Schoenegger

Product Marketing

Name Michael Loeffler

Signature

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signed: Michael Loeffler

E-Mail michael.loeffler@rf360jv.com

Customer feedback

Customer acknowledgement

Signature